

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

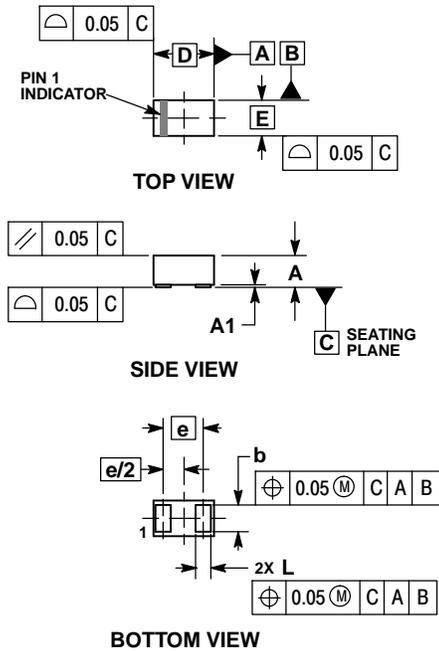
ON Semiconductor®



SCALE 8:1

DSN2, 1.0x0.6, 0.65P, (0402)
CASE 152AE
ISSUE A

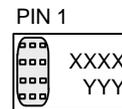
DATE 03 JUN 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

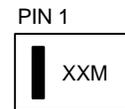
MILLIMETERS		
DIM	MIN	MAX
A	0.25	0.31
A1	---	0.05
b	0.45	0.55
D	1.00 BSC	
E	0.60 BSC	
e	0.65 BSC	
L	0.20	0.30

GENERIC MARKING DIAGRAM1*



XXXX = Specific Device Code
YYY = Year Code

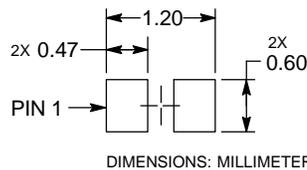
GENERIC MARKING DIAGRAM2*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

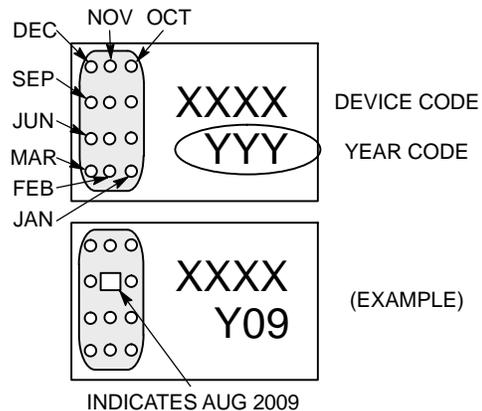
RECOMMENDED SOLDER FOOTPRINT*



See Application Note AND8398/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

CATHODE BAND MONTH CODING



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NEW STANDARD:		
DESCRIPTION:	DSN2, 1.0X0.6, 0.65P, (0402)	PAGE 1 OF 2

